

Remarks

Claims 1-9, 11-18 and 20-22 are pending. Claims 1, 11 and 18 are herein amended and claims 21-22 are added. Applicants submit that the amendments do not add new material to the current Application. Support for the amendments made to claims 1, 11 and 18 can be found on at least page 9, line 23 to page 11, line 21. Claims 21 and 22 are similar, if not identical, to original claims 10 and 19.

Furthermore, no amendment made is related to the statutory requirements of patentability unless expressly stated herein. No amendment made is for the purpose of narrowing the scope of any claim, unless Applicants argue herein that such amendment is made to distinguish over a particular reference or combination of references. For example, the amendment replacing "in contact with" with "over" is a broadening amendment because two items can be over each other and not in contact with each other. In other words, "in contact with" is a subset of "over."

Applicants respectfully submit claims 1-9, 11-18 and 20-22 are patentable over Lee (U.S. 6,222,212) under 35 U.S.C. 102(e) and 35 U.S.C.103(a). The Examiner contends that Lee's substrate 803 can be a packaging material because a packaging material includes a semiconductor substrate. Claims 1, 11 and 18 herein state that the packaging material is either a mold compound or an underfill. Lee fails to teach or suggest that substrate 803 is a mold compound or an underfill. As described in Applicants specification from page 9, line 23 to page 11, line 21, a mold compound is used to form a wirebonded package and an underfill is used to form a ball-grid array or flip-chip package. Lee fails to teach or suggest forming any package and especially fails to teach or suggest that substrate 803 is a mold compound or an underfill. Lee only teaches forming two substrates and electrically connecting them. For at least these reasons, claims 1, 11 and 18 are patentable over Lee under 35 U.S.C. 102(e) and 35 U.S.C. 103(a).

Furthermore, the Examiner's rejections of any dependent claim over Lee are moot because Lee fails to teach or suggest at least the features of the dependent claims that are state in independent claims 1, 11 and 18. Thus, all dependent claims are patentable for at least the reasons discussed above.

Believing to have responded to every issue raised by the Examiner, Applicants believe the present Application is currently in a condition of allowance. Applicants thank the Examiner for pointing out allowable subject matter, but herein earnestly solicit allowance of all pending claims. Please contact Applicant's practitioner listed below if there are any issues.

Respectfully submitted,

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